

ESD Protection - In-Vehicle Networks

Automotive Qualified Low Capacitance High Speed Data Network Protection

SZESD9901

The SZESD9901 protects sensitive automotive electronics from ESD, Surge, and other harmful transient events. This device is designed for compliance to OPEN Alliance 100/1000 BASE-T1 Ethernet, and other high speed data networks. Device is suitable for ESD protection on the connector side of the transceiver PHY.

Features

- High Trigger Voltage ≥ 100 V
- X2DFN 1.0 x 0.6 mm Package
- Wettable Flank Package for Optimal Automated Optical Inspection (AOI)
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Open Alliance 100/1000 BASE-T1 Ethernet
- In Vehicle Networking (IVN)
- High Speed Data Networks

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Operating Junction Temperature Range	T_J	-55 to +150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^\circ\text{C}$
Lead Solder Temperature – Maximum (10 Seconds)	T_L	260	$^\circ\text{C}$
IEC 61000-4-2 Contact (ESD) IEC 61000-4-2 Air (ESD) ISO 10605 150 pF / 330 Ω Contact* ISO 10605 330 pF / 330 Ω Contact ISO 10605 330 pF / 2 k Ω Contact ISO 10605 150 pF / 2 k Ω Contact * minimum number of discharges > 1000	ESD	± 30 ± 30 ± 30 ± 30 ± 30 ± 30	kV
Maximum Peak Pulse Current 8/20 μs	I_{pp}	2.2	A

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Complies with the Following Standards:

- ISO7637-2, Jumpstart, Load Dump
- Open Alliance 100/1000 BASE-T1 Ethernet
- ISO7637-3, Pulse 2a 85 V, 3a 3b 150 V



ON Semiconductor®

www.onsemi.com

MARKING DIAGRAM



X2DFNW2
CASE 711BG



DA = Specific Device Code
M = Date Code

PIN CONNECTIONS

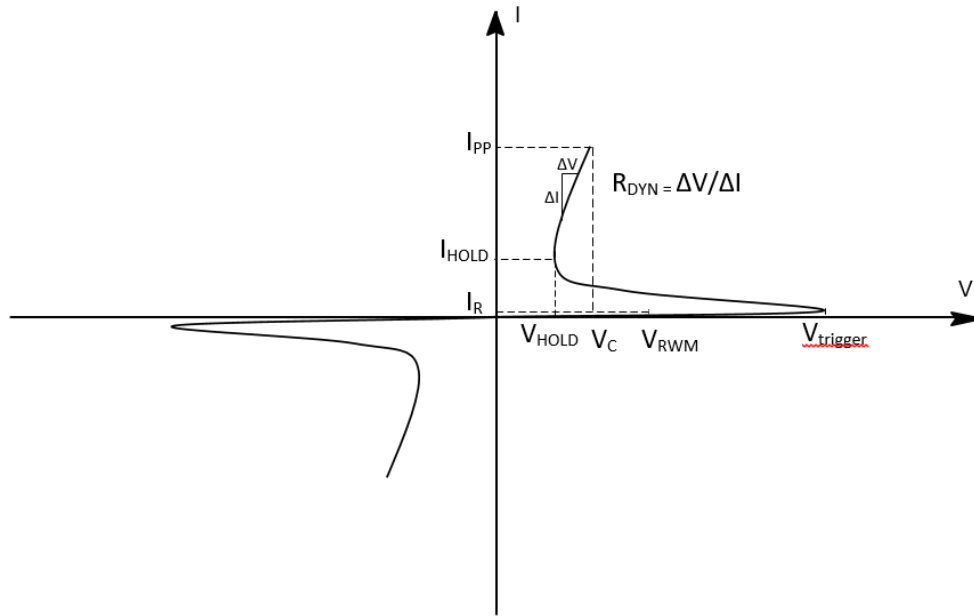


ORDERING INFORMATION

Device	Package	Shipping†
SZESD9901MX2WT5G	X2DFNW2 (Pb-Free)	8,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

SZESD9901



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Working Voltage	V _{RWM}	I/O Pin to GND			25	V
Reverse Leakage Current	I _R	V _{RWM} = 25 V		1	200	nA
Reverse Holding Voltage	V _{HOLD}	I/O Pin to GND	25			V
ESD Trigger Voltage (Note 2)	V _{trigger}		100			V
Reverse Peak Pulse Current	I _{PP}	per IEC61000-4-5 (8x20 μs)			2.2	A
Channel Capacitance	C _{Jio-gnd}	V _R = 0 V, f = 1 MHz		2.3	2.6	pF
Dynamic Resistance (Note 2)	R _{DYN}	I/O to GND, GND to I/O		0.4		Ω

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- For test procedure see Figure 6 and application note AND8307/D.
- ANSI/ESD STM5.5.1 – Electrostatic Discharge Sensitivity Testing using Transmission Line Pulse (TLP) Model.
TLP conditions: Z₀ = 50 Ω, t_p = 100 ns, t_r = 1 ns, averaging window: t₁ = 70 ns to t₂ = 90 ns.

SZESD9901

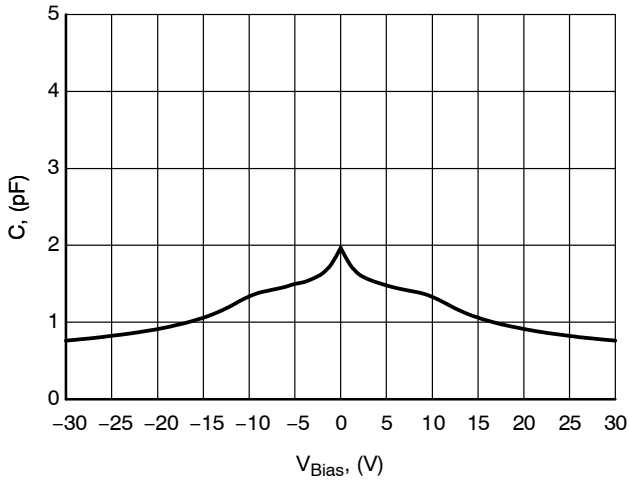


Figure 2. CV Characteristics

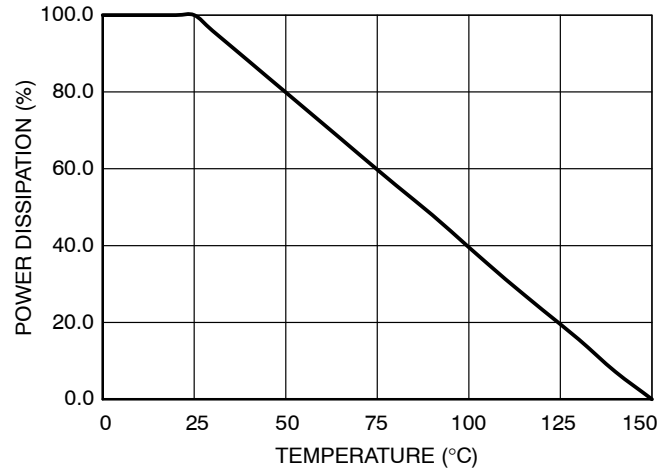


Figure 3. Steady State Power Derating

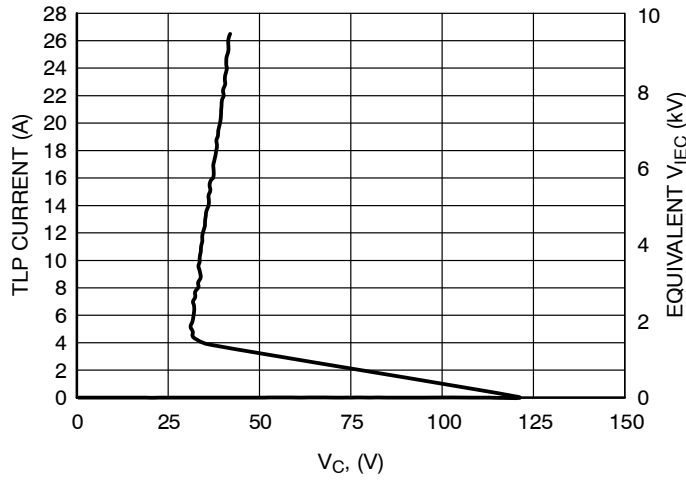


Figure 4. Positive TLP IV Curve

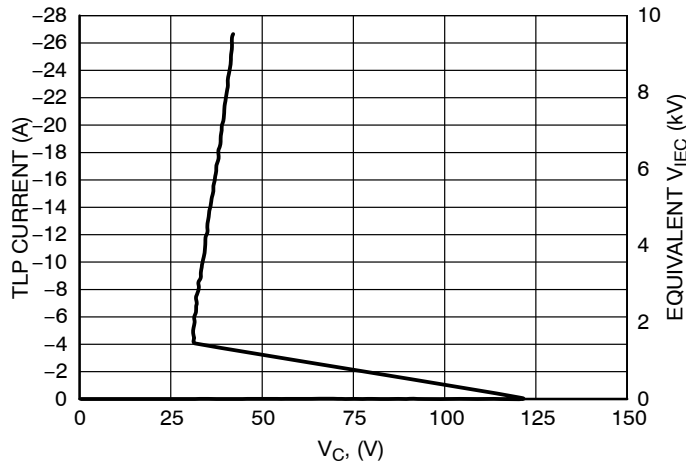


Figure 5. Negative TLP IV Curve

SZESD9901

IEC 61000-4-2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

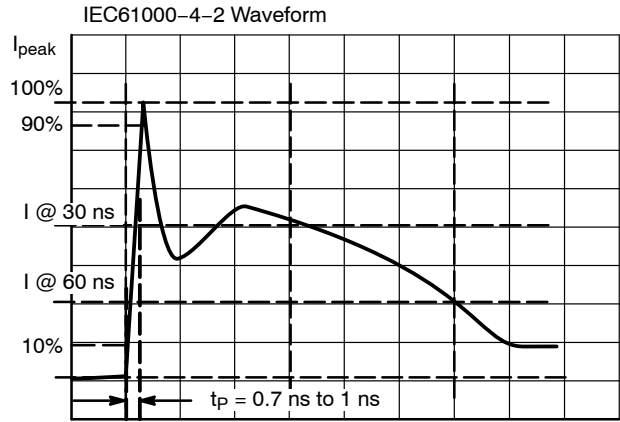


Figure 6. IEC61000-4-2 Spec

Transmission Line Pulse (TLP) Measurement

Transmission Line Pulse (TLP) provides current versus voltage (I-V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 7. TLP I-V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 8 where an 8 kV IEC 61000-4-2 current waveform is compared with TLP current pulses at 8 A and 16 A. A TLP I-V curve shows the voltage at which the device turns on as well as how well the device clamps voltage over a range of current levels.

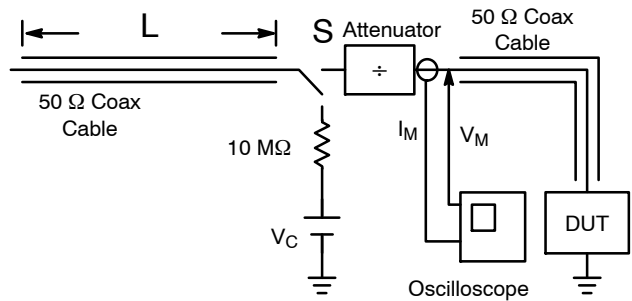


Figure 7. Simplified Schematic of a Typical TLP System

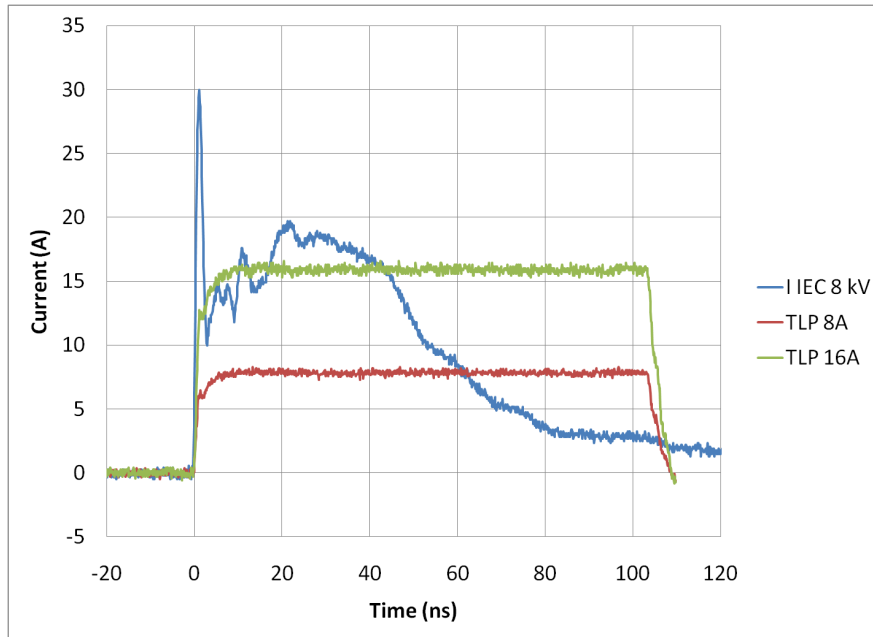


Figure 8. Comparison Between 8 kV IEC 61000-4-2 and 8 A and 16 A TLP Waveforms

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

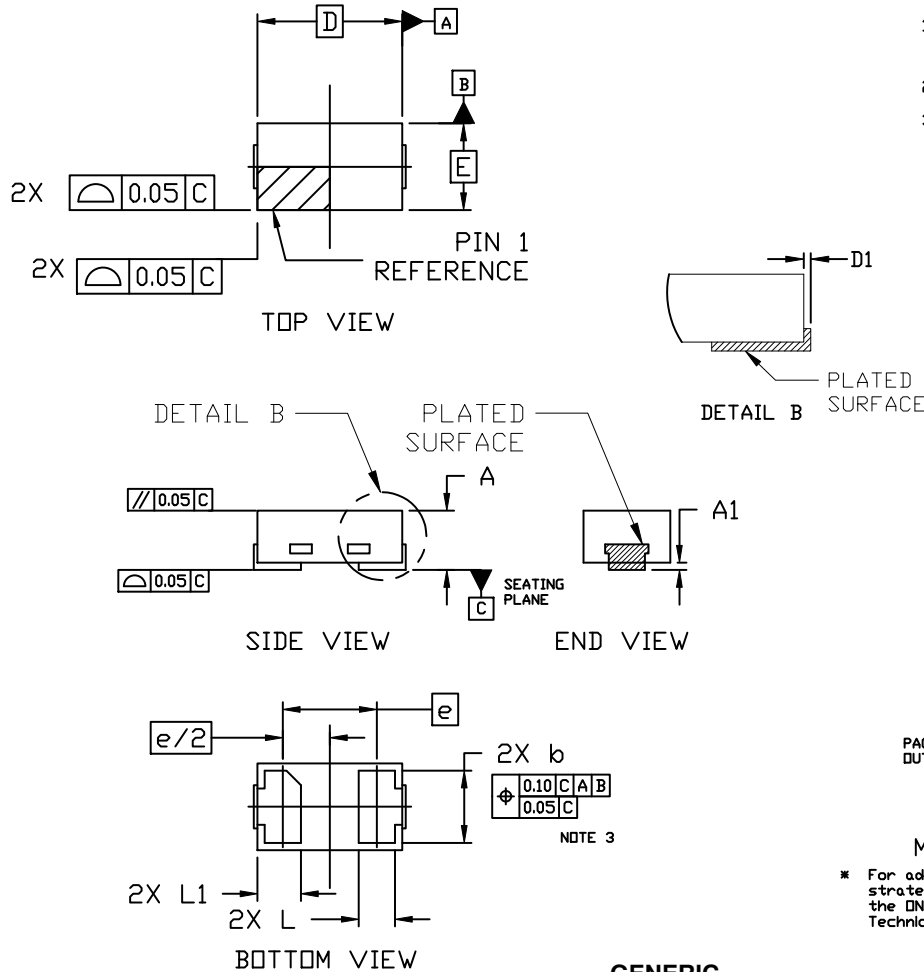
ON Semiconductor®



SCALE 8:1

X2DFNW2 1.0x0.6, 0.65P
CASE 711BG
ISSUE C

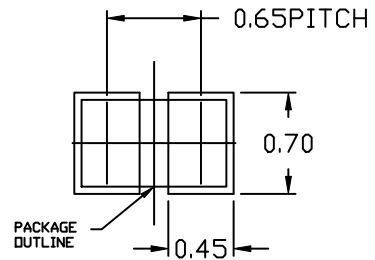
DATE 13 SEP 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION *b* APPLIES TO THE PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 FROM THE TERMINAL TIP.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.34	0.37	0.40
A1	---	---	0.05
b	0.45	0.50	0.55
D	0.90	1.00	1.10
D1	---	---	0.05
E	0.50	0.60	0.70
e	0.65 BSC		
L	0.22 REF		
L1	0.24	0.285	0.34



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	98AON15241G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	X2DFNW2 1.0X0.6, 0.65P	PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative